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**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 1792**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of

Shigehiro NISHINO et al.

Group Art Unit: 1792

Application No.: 10/520,141

Examiner: M. SONG

Filed: September 1, 2005

Docket No.: 122261

For: LARGE-DIAMETER SIC WAFER AND MANUFACTURING METHOD THEREOF

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the November 26, 2008 Office Action, please consider the following:

**Amendments to the Claims** as reflected in the listing of claims; and

**Remarks.**